

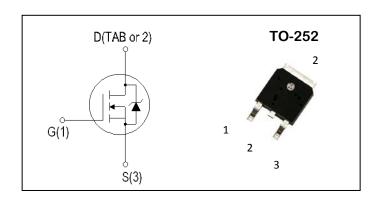
N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

V _{DSS}	I_D $R_{DS(ON)}$ $(m\Omega)$	
30V	40A	10m $Ω$

Features:

- Low Gate Charge for Fast Switching Application
- Low Rds(ON) to Minimize Conductive Loss
- 100% EAS Guaranteed
- Optimized V(BR)DSS Ruggedness
- Lead-Free,RoHS Compliant



Description:

The ADM40N30E uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. It can be used in a wide variety of applications.

Absolute Maximum Ratings (TA = 25°C unless otherwise specifed)

Symbol	Parameter		Ratings	Unit	
Common Ratings					
V _{DSS}	Drain-Source Voltage		30	V	
V _{GSS}	Gate-Source Voltage		±20V	V	
TJ	Maximum Junction Temperature		175	°C	
T _{STG}	Storage Temperature Range		-55 to175	°C	
ls	Diode Continuous Forward Current	T _C =25°C	40	Α	
Mounted o	n Large Heat Sink		·		
Ірм	300µs Pulse Drain Current Tested (2)	T _C =25°C	160	А	
In Co	Continuous Drain Current (1)	T _C =25°C	40	Α	
		T _C =100°C	26	А	
PD	Maximum Power Dissipation	T _C =25°C	29	W	

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
RthJC	Thermal resistance junction-case max (1)	5.2	°C/W
RthJA	Thermal resistance junction-ambient max (1)	68	°C/W

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ADM40N30E

Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
On/off Charac	teristics					•
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250uA	30			V
IDSS	Zero Gate Voltage Drain Current	V _{DS} =30V,V _{GS} =0V , T _J =25°C			1.0	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250uA	1.0	1.5	2.5	V
Igss	Gate Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
D		V _{GS} = 10V, I _{DS} =20A		7.6	10	mΩ
Rds(on)	Drain-SourceOn-stateResistance (2)	V _{GS} = 4.5V, I _{DS} =10A		11.5	17	
Dynamic Chara	cteristics					•
Ciss	Input Capacitance	V _{GS} =0V,		1011		
Coss	Output Capacitance	V _{DS} =15V,		142		pF
Crss	Reverse Transfer Capacitance	Frequency=1MHz		119		
Switching Char	acteristics					•
td(ON)	Turn-on Delay Time	V _{DS} =30V,		6		
t r	Turn-on Rise Time	I _D = 2A, V _{GS} = 10V,		5		
td(OFF)	Turn-off Delay Time	R _{GEN} =3 Ω		25		nS
tf	Turn-off Fall Time			7		
Qg	Total Gate Charge	V _{DS} =15V, V _{GS} = 10V,		19		
Qgs	Gate-Source Charge	I _{DS} =20A		6.3		nC
Qgd	Gate-Drain Charge			4.5		
Avalanche Ch	aracteristics					
EAS	Single Pulse Avalanche Energy (3)	L=0.5mH , T _C =25°C			29	mJ
Diode Charact	eristics					
VsD	Diode Forward Voltage (2)	I _{SD} = 30A, V _{GS} = 0			1.2	V
trr	Reverse Recovery Time	1 204 -11 /-14 4004/ -		7		ns
q rr	Reverse Recovery Charge	I _{SD} =30A, dI _{SD} /dt=100A/μs		6.3		nC

NOTES:

^{1.} Surface Mounted on FR4 Board, $t \le 10$ sec.

^{2.}The data tested by pulsed , pulse width $\,\leq\,\,300\text{us}$, duty cycle $\,\leq\,\,0.5\%$

^{3.}The Min. value is 100% EAS tested guarantee. T_J=25 $^{\circ}$ C, V_{DD}=15V, V_G=10V, R_G=25 $^{\circ}$ C, L=0.5mH, I_{AS}=10.8A



Typical Performance Characteristics

Figure 1: On-Region Characteristics

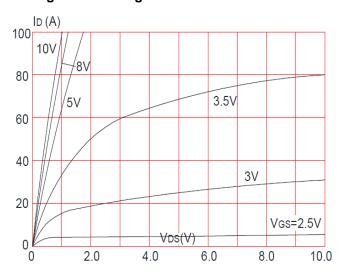


Figure 3: Rdson- Drain Current

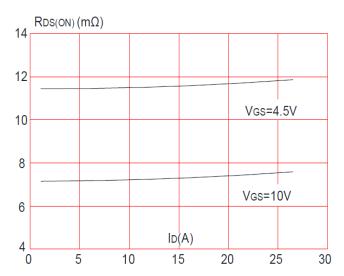


Figure 5: Source- Drain Diode Forward

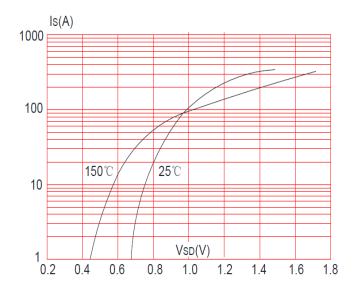


Figure 2: Transfer Characteristics

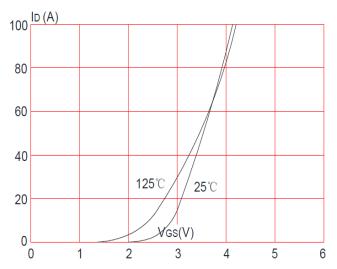


Figure 4: Normalized on Resistance vs. Junction Temperature

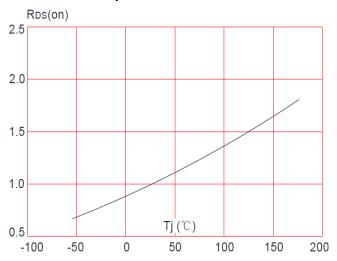


Figure 6: Gate Charge Characteristics

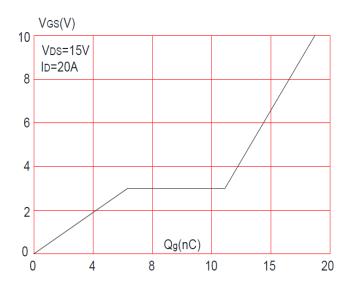




Figure 7: Capacitance vs Vds

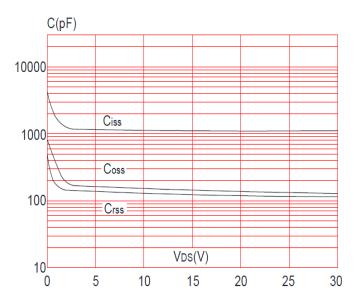


Figure 9: Maximun Drain Current vs. Case Temperature

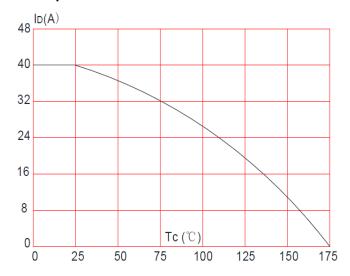


Figure 8: Safe Operation Area

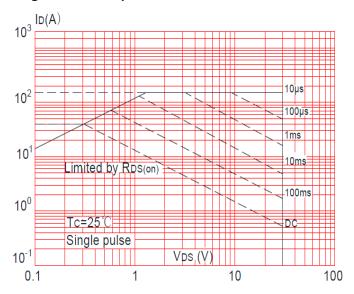


Figure 10: Normalized Breakdown Voltage vs. Junction Temperature

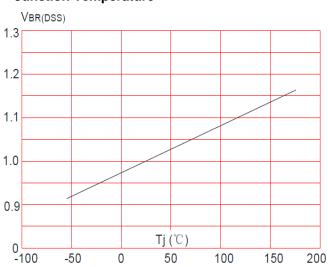
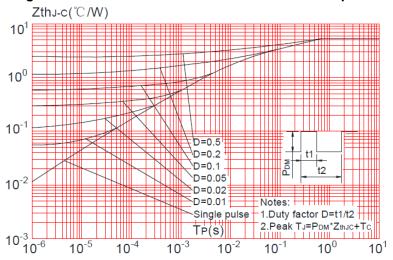


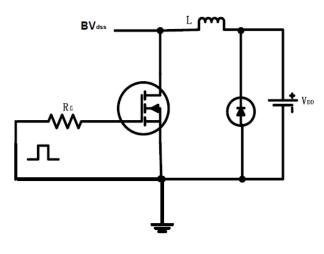
Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



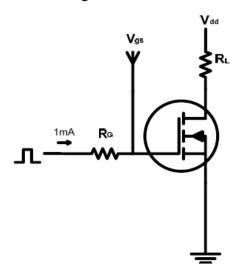


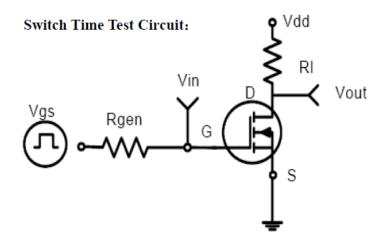
Test circuits and Waveforms

EAS test circuits:

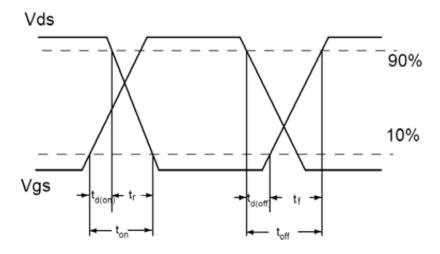


Gate charge test circuit:



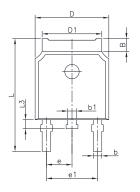


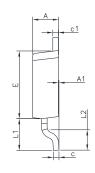
Switch Waveforms:

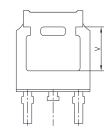




PACKAGE MECHANICAL DATA TO-252-2 Package Dimension







Cumb	Dimensions		Dimensions		
Symb ol	In Millimeters		In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
В	1.070	1.220	0.042	0.048	
b	0.720	0.850	0.028	0.033	
b1	0.720	0.850	0.028	0.033	
С	0.450	0.620	0.017	0.024	
c1	0.450	0.620	0.017	0.024	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
Е	5.900	6.200	0.232	0.244	
е	2.300 TYP.		0.091 TYP.		
e1	4.500	4.700	0.177	0.185	
L	9.500	10.60	0.374	0.396	
L1	2.550	2.900	0.100	0.114	
L2	1.400	1.780	0.055	0.070	
L3	0.600	0.900	0.024	0.035	
V	3.950 REF.		0.155	REF.	

Ordering information

Part number	Package	Marking	Packing	Quantity
ADM40N30E	TO-252-2	ADM40N30E	Tube	80pcs
			Embossed tape	2500pcs



ADM40N30E

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